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TECHNICAL REPORT

EMC IC modelling -
Part 4-1: Use of ICIM-CI model to predict the IC conducted immunity in a PCB

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IEC Secretariat
3, rue de Varembé
CH-1211 Geneva 20
Switzerland

Tel.: +41 22 919 02 11
info@iec.ch
www.iec.ch

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EMC IC modelling - Part 4-1: Use of ICIM-CI model to predict the IC conducted immunity in a PCB

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